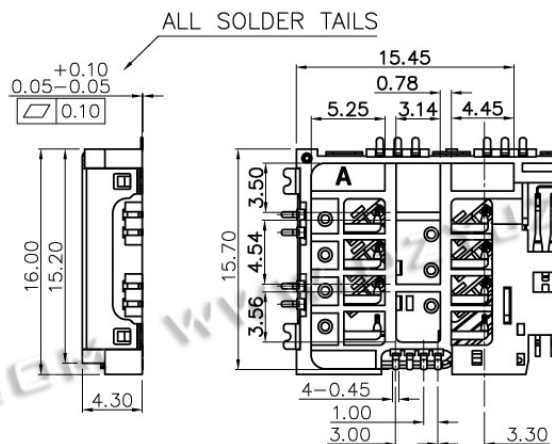
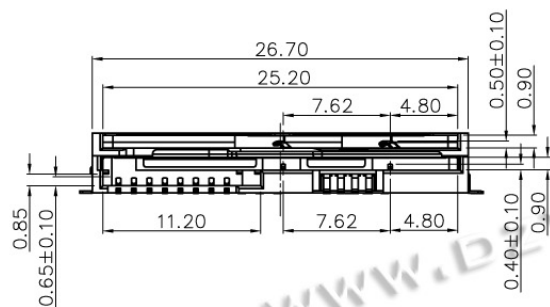
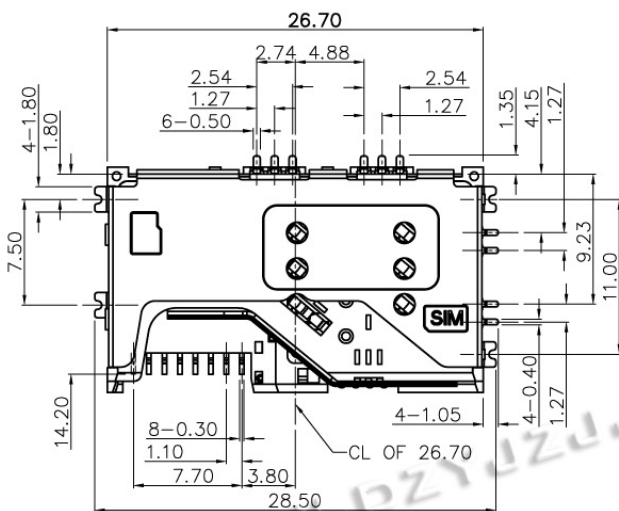


NOTES:

1.Material:

- 1.1 Housing:Thermoplastic UL94-v0 Black;
- 1.2 Terminal:Coppy Alloy;
- 1.3 Shell:Stainless steel
- 1.4 Slide:Stainless steel

2.Finish:

- 2.1 Au On The Contact Area and Solder Tails;
- 2.2 Shell: Selective Au On The Solder Tails.

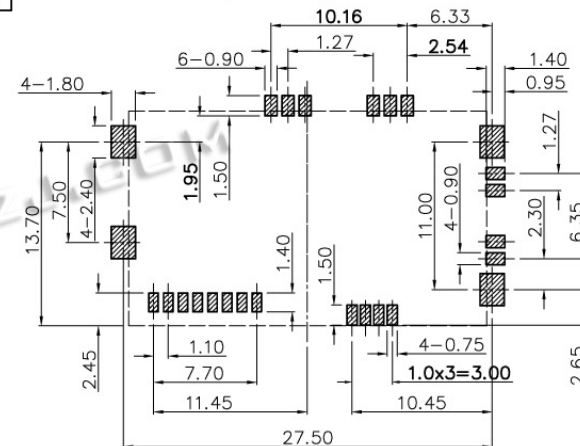
3.Electrical Performance:

- 3.1 Current Rating: 0.5A
- 3.1 Contact Resistance:80mΩ Max;
- 3.2 Dielectric Withstanding Voltage:250V AC rms for 1 minut;
- 3.3 Insulation Resistance:1000 MΩ Min;

4.Mechanical Performance:

- 4.1 Durability:5000 cycles;

5.PACKING:Tape&Reel;



RECOMMENDED P.C.BOARD LAYOUT (TOP VIEW)

TOLERANCES UNLESS OTHERWISE SPEC.±0.05

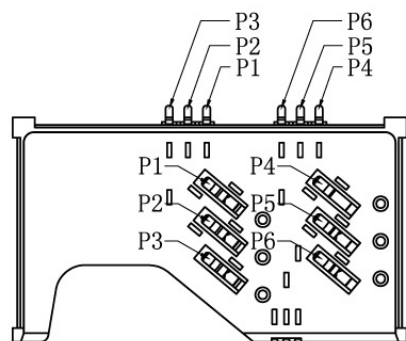


KEEP OUT AREA



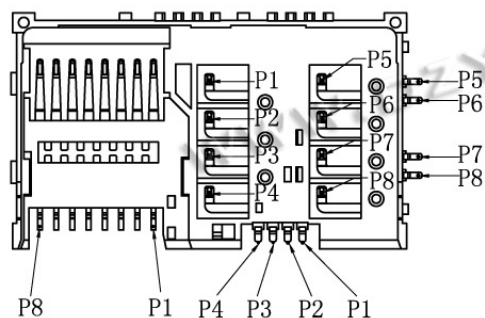
深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2° X.X' ±0.5°	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: TF+双SIM三合一卡座
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC19-3IN122-267
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱国夷	DATE : 2014-02-23	MOLD NO.
			DRAW NO: HYC-IN115101614
			SHEET NO. 1 OF 1



P1	GND
P2	VPP
P3	I/O
P4	VCC
P5	RST
P6	CLK

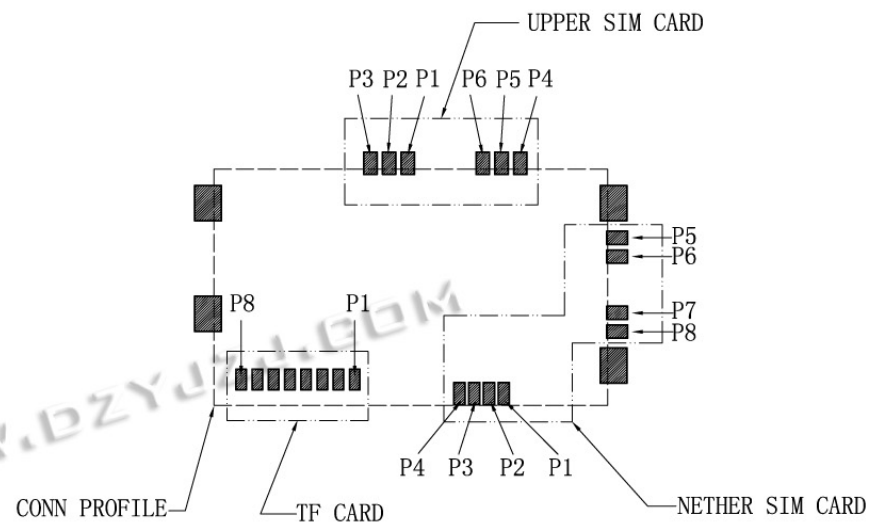
UPPER SIM CARD CIRCUIT



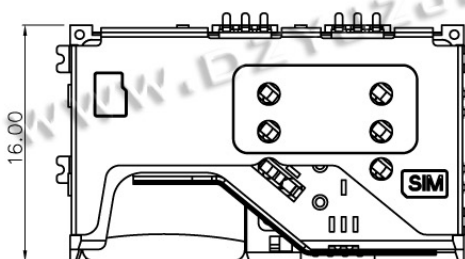
P1	GND
P2	VPP
P3	I/O
P4	RESERVED
P5	VCC
P6	RST
P7	CLK
P8	RESERVED

TF CARD+NETHER SIM CARD CIRCUIT

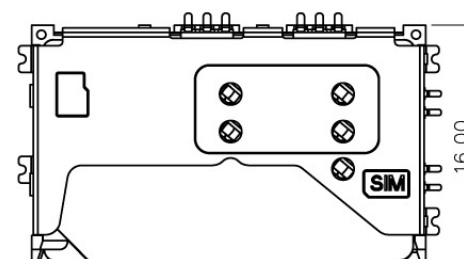
P1(T)	DAT2
P2(T)	CD/DAT3
P3(T)	CMD
P4(T)	VDD
P5(T)	CLK
P6(T)	VSS
P7(T)	DAT0
P8(T)	DAT1



PCB LAYOUT PIN ASSIGNMENT



MALE T-FLASH CARD SCHEMATIC



MALE SIMCARD SCHEMATIC



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5" UNIT: mm [inch] SCALE:1:1 SIZE: A4	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: TF+双SIM三合一卡座
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			SHEET NO. 1 OF 1